

HIGH-DENSITY CONNECTION BETWEEN MULTIPLE CIRCUIT BOARDS

ABSTRACT OF THE DISCLOSURE

5 A high-density connection of multiple circuit boards having overlapping ends arranged in a stack. The metal traces on the stacked circuit boards are electrically connected by contact of the ends of the traces, which ends may be pads. The stacked circuit boards can be clamped, soldered or bonded together. Multiple circuit boards may be connected to a single circuit board. In one embodiment, double-sided circuit boards are stacked so that a first circuit board connects to a second circuit board through a third circuit board disposed intermediate the first and second circuit boards. The circuit boards may be flexible or rigid.